The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (previously presented) An integrated circuit package, comprising:

a first die with a conductive side;

a plurality of lead posts, wherein the conductive side of the first die faces the plurality of lead posts, each of the lead posts positioned on a plurality of lead fingers respectively, each of the plurality of lead fingers electrically isolated from one another; and

an encapsulating material encapsulating the first die, the lead posts and formed between the plurality of lead fingers to electrically isolate the lead fingers from one another.

2. (original) The integrated circuit package, as recited in claim 1, wherein the conductive side of the first die is mechanically and electrically connected to the plurality of lead posts.

3. (original) The integrated circuit package, as recited in claim 2, wherein the conductive side comprises a plurality of spaced apart conductive pads, which are mechanically and electrically connected to the lead posts.

4. (original) The integrated circuit package, as recited in claim 3, wherein the plurality of conductive pads is mechanically and electrically connected to the lead posts by conductive epoxy.

5. (original) The integrated circuit package, as recited in claim 2, wherein the lead posts have equal spacing and pitch.

6. (original) The integrated circuit package, as recited in claim 2, wherein the lead posts have a square cross section.

7. (original) The integrated circuit package, as recited in claim 2, wherein the lead posts have a round cross section.

8. (original) The integrated circuit package, as recited in claim 2, wherein the lead posts have lengths which are substantially perpendicular to the conductive side of the first die.

9. (original) The integrated circuit package, as recited in claim 2, further comprising a second die with a conductive side and a side opposite the conductive side, wherein the side opposite the conductive side is connected to a side opposite the conductive side of the first die.

10. (original) The integrated circuit package, as recited in claim 9, further comprising wirebonding connected between the conductive side of the second die and at least one lead post of the plurality of lead posts.

11. (previously presented) An integrated circuit package comprising:

an array of lead posts that are equally spaced apart, each of the lead posts positioned on a an array of lead fingers, each of the lead fingers electrically isolated from one another, each of the lead posts further having an oversized contact pad on a bottom surface of the integrated circuit package, wherein each oversized contact pad has a diameter that is larger than a diameter of a respective lead post;

a first die having a conductive side that is electrically and mechanically connected to at least some of lead posts within the array of lead posts, wherein the conductive side of the first die faces the lead posts; and

an encapsulating material that encapsulates the first die and between the individual lead fingers of the array of lead fingers.

12. (original) An integrated circuit package as recited in claim 11 wherein the conductive side of each of the first dice is in direct contact with at least some of the lead posts.

13. (original) An integrated circuit package as recited in claim 11, further comprising:

a second die that is attached to the first die, wherein the second die has a conductive side and a side opposite the conductive side, wherein the side opposite the conductive side of each second die is connected to a side opposite the conductive side of the first die, wherein the second die has a plurality of conductive pads on the conductive side of the second die; and

interconnecting wires that connect the conductive pads of the second die to lead posts of the array of lead posts, wherein the encapsulating material also encapsulates the second die and each of the interconnecting wires.

14. (original) An integrated circuit package as recited in claim 11 wherein the encapsulating material has a top and a bottom surface and wherein each of the oversized contact pads are formed on the bottom surface of the encapsulating material.

15. (original) An integrated circuit package as recited in claim 11 wherein each of the oversized contact pads have a substantially square outline.

16. (previously presented)An apparatus, comprising,

a lead frame having a substantially continuous and planer first surface and a plurality of posts formed on the second surface;

a semiconductor die having an active surface, the active surface having a plurality of conductive pads in contact with the plurality of posts of the lead frame respectively;

an encapsulant material encapsulating the semiconductor die and the plurality of posts in contact with the plurality of conductive pads on the semiconductor die, the substantially continuous and planer second surface of the lead frame acting to prevent the encapsulant from forming on the second surface of the lead frame.

17. (previously presented)The apparatus of claim 16, wherein the encapsulant is formed between the plurality of posts.

18. (previously presented) The apparatus of claim 16, further comprising a conductive epoxy between the plurality of posts and the plurality of conductive pads respectively.

19. (previously presented) An apparatus, comprising:

a lead frame having a first surface and a substantially planar second surface,

a set of posts formed on the first surface of the lead frame, the plurality of post organized into a plurality of sub-sets of posts,

a plurality of semiconductor die, each of the plurality of die having conductive pads mounted onto the plurality of sub-sets of posts respectively; and

continuous encapsulant material encapsulating the lead frame including the plurality of semiconductor die and the plurality of sub-sets of posts, the substantially planer second surface of the lead frame acting to prevent the encapsulant from forming on the second surface of the lead frame.

20. (previously presented) The apparatus of claim 19, conductive epoxy provided between the plurality of posts and the plurality of conductive pads of the semiconductor die respectively.

21. (previously presented) The apparatus of claim 19, further comprising a space formed between the plurality of semiconductor die mounted onto the sub-sets of posts of the lead frame respectively, the space being sufficient to singulate the individual semiconductor die from the lead frame using a cutting tool.